

SOLDER ALLOY, SOLDER PASTE, AND SOLDER JOINT

ABSTRACT

Provided are a solder alloy, a solder paste, and a solder joint that exhibit a suitable melting temperature, are excellent in wettability, are high in tensile strength and shear strength, and are further excellent in drop impact resistance. The solder alloy has the following alloy composition. The alloy composition has an alloy composition consisting of, by mass%, Ag: 0.1 to 3.9%, Cu: 0.1 to 1.0%, Bi: 0.6 to 1.4%, Sb: 5.1 to 7.9%, Ni: 0.01 to 0.30%, Co: 0.001 to 0.100% or less, with the balance being Sn.

[Figure 1]